
GooLED

# GooLED-8630 Pin Fin LED Heat Sink Φ86.5mm

## Features VS Benefits

* Mechanical compatibility with direct mounting of the LED modules to the LED cooler and thermal performance matching the lumen packages.
* For spotlight and downlight designs from 1,200 to 3,200 lumen.
* Thermal resistance range Rth 2.5°C/W.
* Modular design with mounting holes foreseen for direct mounting of a wide range of LED modules and COB's:
* Diameter 86.5mm - Standard height 30.0mm , Other heights on request.
* Forged from highly conductive aluminum.
* 2 standard colors - clear anodised - black anodised.
* Zhaga Book 3 Spot Light modules: Bridgelux ,Cree ,Citizen ,Edison ,GE lighting, LG Innotek ,Lumileds ,Lumens ,Luminus ,Nichia ,Osram ,Philips ,Prolight Opto, Samsung ,Seoul ,Tridonic ,Vossloh-Schwabe ,Xicato.

01) Bridelux: Vero 18/22 Vero SE 18/29 LED engines;
02) Cree: XLamp CXA 25xx, Xlamp CXB 25xx, CXA 30xx, Xlamp CXB 30xx LED eng
03) Citizen: CLU036, CLU038, CLU721, CLU711, CLU046, CLU048, CLU731 LED engines;
04) Edison: EdiLex III COB LED engines;
05) GE lighting: Infusion™ LED engines;
06) LG Innotek: 32W, 42W, 56W LED engines;
07) LumiLEDS: LUXEON 1211, LUXEON 1216, LUXEON 1812, LUXEON 1825 LED eng
08) Lumens: Ergon-COB-2530, 2540, 3050, 3070 LED engines;
09) Luminus: CXM-18, CLM-22, CXM-22 LED engines;
10) Nichia: NFCWL036B, NFCLL036B, NFCWL060B, NFCLL060B LED engines;
11) Osram: SOLERIQ® S 19, Core series LED engines;
12) Philips: Fortimo SLM LED engines;
16) Prolight Opto: PABS, PABA, PACB, PANA LED engines;
13) Samsung: LC026B, LC033B, LC040B, LC040D, LC060D, LC080D LED engines;
14) Seoul Semiconductor: Acrich MJT COBs, DC COB LED engines;
15) Tridonic: SLE G6 19mm, SLE G6 23mm LED engines;
17) Vossloh-Schwabe: LUGA Shop and LUGA C LED engines;
18) Xicato: XSM, XIM,XTM LED engines;

## Order Information

**Example:GooLED-8630-B**

**Example:GooLED-8630-1**

**1 Anodising Color**
**B-Black**
**C-Clear**
**Z-Custom**

### Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

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## GooLED-8630 Pin Fin LED Heat Sink Φ86.5mm

### The product deta table


| | |
|---|---|
| **Model No.** | **GooLED-8630** |
| **Heatsink Size** | **Φ86.5xH30mm** |
| **Heatsink Material** | **AL1070** |
| **Finish** | **Black Anodized** |
| **Weight (g)** | **152.0** |
| **Dissipated power (Ths-amb,50℃)** | **20.0 (W)** |
| **Cooling surface area ($mm^2$)** | **48926** |
| **Thermal Resistance (Rhs-amb)** | **2.5 (°C/W)** |

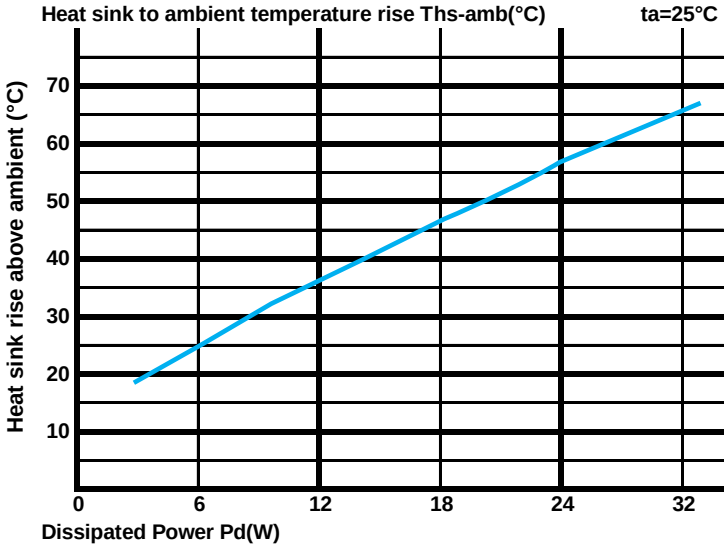
### The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

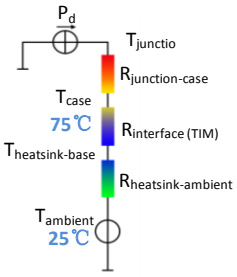
| Pd = Pe x (1-ηL) | | Heat sink to ambient thermal resistance Rhs-amb (°C/W) | Heat sink to ambient temperature rise Ths-amb (°C) |
|---|---|---|---|
| | | GooLED-8630 | |
| Dissipated Power Pd(W) | 6.0 | 4.00 | 24.0 |
| | 12.0 | 2.92 | 35.0 |
| | 18.0 | 2.56 | 46.0 |
| | 24.0 | 2.33 | 56.0 |
| | 32.0 | 2.03 | 65.0 |




*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.




*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: θ =(Ths−Ta)/Pd

θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface\ (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface\ (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is also used:

$T_{junction}=(R_{junction-case}+R_{case-ambient})\cdot Pd+T_{ambient}$

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